



PATENT  
Attorney Docket No. 207617

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4/2/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Dirksen et al.

Application No. 09/737,905

Art Unit: 1765

Examiner: V. Perez-Ramos

Filed: December 15, 2000

For: METHOD OF POLISHING OR  
PLANARIZING A SUBSTRATE

COPY OF PAPERS  
ORIGINALLY FILED

RESPONSE TO OFFICE ACTION

Commissioner for Patents  
Washington, D.C. 20231

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TC 1700

Dear Sir:

In response to the Office Action dated December 31, 2001, please consider the following remarks.

REMARKS

*The Pending Claims*

Claims 1-16 are currently pending. Claims 1-16 are directed to a method of polishing a substrate with a composition comprising a metal oxide abrasive and a liquid carrier, wherein the composition has a pH of about 7 or less and the metal oxide abrasive has a total surface hydroxyl group density no greater than about 3 hydroxyl groups per nm<sup>2</sup>. Reconsideration of the pending claims is respectfully requested.

*Summary of the Office Action*

Claims 1-16 stand rejected under 35 U.S.C. § 103(a) as obvious over Adams et al. (i.e., U.S. Patent 5,664,990) and Kaneko et al. (i.e., U.S. Patent 5,114,881).

*Discussion of the Obviousness Rejection*

The Office Action asserts that Adams et al. discloses polishing compositions for metal-containing substrates comprising a metal oxide abrasive and a liquid carrier at a pH of less than 5. The Office Action further asserts that Kaneko et al. discloses silica powder having a hydroxyl density of 0.1 to 4 groups/100 Å<sup>2</sup>. While the Office Action acknowledges that Adams et al. fails to disclose the use of a metal oxide abrasive having a total surface